ABSTRACT OF THE DISCLOSURE

METAL CORE FOLDOVER PACKAGE STRUCTURES, SYSTEMS INCLUDING SAME AND METHODS OF FABRICATION

Chip scale packages and assemblies thereof and methods of fabricating such packages including Chip-On-Board, Board-On-Chip, and vertically stacked Package-On-Package modules are disclosed. The chip scale package includes a core member of a metal or alloy having a recess for at least partially receiving a die therein and includes at least one flange member partially folded over another portion of the core member. Conductive traces extend from one side of the package over the at least one flange member to an opposing side of the package. Systems including the chip scale packages and assemblies are also disclosed.

[FIG. 1]